

Please amend the application as follows.

In the Specification

Please replace the paragraph on page 11, lines 1 through 13 with the following paragraph, and the replaced paragraph is also shown in re-written form, with underlining showing additions and brackets showing deletions, on a sheet attached to this Amendment and filed herewith:

B1

As defined herein, the term "profile" refers to thickness or height of, for example, the integrated circuit package of the present invention. The integrated circuit package of the present invention may be measured in, for example, mils. As defined herein, the term "substantially similar" refers to the relative outlines of the printed circuit board and the silicon chip, which are within less than about 10% of one another. In one embodiment of the present invention, the difference in the outlines is about 2%. In an alternative embodiment, the silicon chip and the printed circuit board have the same outlines. Importantly, the term substantially similar does not indicate which of the two components is larger, as either form is encompassed by the present invention.